

| | | | |
|---|---|--|------------------|
| PCN Number: | 20220720000.1 | PCN Date: | July 20, 2022 |
| Title: | Qualification of TSMC-WF3 (Fab 3) as an additional Wafer Fab Site option for select devices | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Proposed 1st Ship Date: | Oct 20, 2022 | Sample requests accepted until: | August 20, 2022* |

***Sample requests received after August 20, 2022 will not be supported.**

Change Type:

| | | | | | |
|-------------------------------------|-----------------|--------------------------|---------------------------|--------------------------|--------------------------|
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Assembly Process | <input type="checkbox"/> | Assembly Materials |
| <input type="checkbox"/> | Design | <input type="checkbox"/> | Electrical Specification | <input type="checkbox"/> | Mechanical Specification |
| <input type="checkbox"/> | Test Site | <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | Wafer Bump Site | <input type="checkbox"/> | Wafer Bump Material | <input type="checkbox"/> | Wafer Bump Process |
| <input checked="" type="checkbox"/> | Wafer Fab Site | <input type="checkbox"/> | Wafer Fab Materials | <input type="checkbox"/> | Wafer Fab Process |
| | | <input type="checkbox"/> | Part number change | | |

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TSMC-WF3 (Fab 3) fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

| Current Fab Site | | | Additional Fab Site | | |
|-------------------|-------------|----------------|---------------------|-------------|----------------|
| Current Fab Site | Process | Wafer Diameter | New Fab Site | Process | Wafer Diameter |
| TSMC-WFT (Fab 11) | 0.18UM-TSMC | 200 mm | TSMC-WF3 (Fab 3) | 0.18UM-TSMC | 200 mm |

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:


Current

| | | | |
|-------------------|------------------------|------------------------------|----------------|
| Chip Site | Chip Site Origin (20L) | Chip Site Country Code (21L) | Chip Site City |
| TSMC-WFT (Fab 11) | T13 | USA | Camas |

New Fab Site

| | | | |
|------------------|------------------------|------------------------------|----------------|
| Chip Site | Chip Site Origin (20L) | Chip Site Country Code (21L) | Chip Site City |
| TSMC-WF3 (Fab 3) | TS5 | TWN | Hsinchu |


Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:

| | |
|------------------------|----------|
| MSL '2 / 260C / 1 YEAR | SEAL DT |
| MSL 1 / 235C / UNLIM | 03/29/04 |

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

| | | | |
|-------------|-------------|-------------|--|
| SN3138RGCR | UCD3138RHAR | UCD3138RJAR | |
| UCD3138RGCR | UCD3138RHAT | UCD3138RJAT | |

Qualification Report

Approve Date 08-Jun-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | Test Name / Condition | Duration | Qual Device: UCD3138RGC | Qual Device: UCD3138RJAR | QBS Product Reference: UCD3138RGC | QBS Product Reference: UCD3138RHA | QBS Product Reference: UCD3138RMH | QBS Product Reference: UCD3138RJA | QBS Package Reference: UCD3138ARGC | QBS Package Reference: UCD3138RMH |
|------|-----------------------------|-----------------------------|----------------------------|-----------------------------|---|---|---|---|--|---|
| AC | Autoclave 121C | 96 Hours | - | - | - | - | - | - | 3/231/0 | 2/154/0 |
| ED | Electrical Characterization | Per Datasheet Parameters | 1/30/0 | - | - | - | - | 1/30/0 | - | 1/30/0 |
| HBM | ESD - HBM | 4000 V | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | - | - | - |
| CDM | ESD - CDM | 1000 V | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | 1/3/0 | - | - |
| HTOL | Life Test, 140C | 480 Hours | 1/77/0 | - | 1/77/0 | - | - | - | - | - |
| LU | Latch-up | (per JESD78) | 1/6/0 | - | 1/6/0 | - | - | - | - | - |
| TC | Temperature Cycle, -65/150C | 500 Cycles | 1/77/0 | - | - | - | - | 3/231/0 | 3/230/0 | 2/154/0 |

- QBS: Qual By Similarity

- Qual Device UCD3138RJAR is qualified at LEVEL2-260C

- Qual Device SN3138RGCR is qualified at LEVEL3-260C

- Qual Device UCD3138RGC is qualified at LEVEL2-260C

- Qual Device UCD3138RHAR is qualified at LEVEL3-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contact shown below, or you can contact your local Field Sales Representative.

| Location | E-Mail |
|---------------------------|--|
| WW Change Management Team | PCN_ww_admin_team@list.ti.com |

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